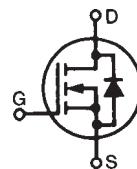
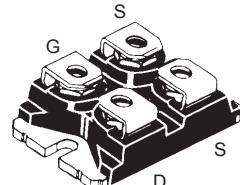


**TrenchMV™**  
**Power MOSFET**
**IXTN200N10T**
**N-Channel Enhancement Mode**  
**Avalanche Rated**

 $V_{DSS} = 100V$   
 $I_{D25} = 200A$   
 $R_{DS(on)} \leq 5.5m\Omega$ 
**miniBLOC, SOT-227 B**  
 **E153432**

**G** = Gate      **D** = Drain  
**S** = Source

Either Source terminal at miniBLOC can be used as Main or Kelvin Source

Symbol	Test Conditions	Maximum Ratings	
$V_{DSS}$	$T_J = 25^\circ C$ to $175^\circ C$	100	V
$V_{DGR}$	$T_J = 25^\circ C$ to $175^\circ C$ , $R_{GS} = 1M\Omega$	100	V
$V_{GSS}$	Continuous	$\pm 20$	V
$V_{GSM}$	Transient	$\pm 30$	V
$I_{D25}$	$T_c = 25^\circ C$	200	A
$I_{LRMS}$	External lead current limit	100	A
$I_{DM}$	$T_c = 25^\circ C$ , pulse width limited by $T_{JM}$	500	A
$I_A$	$T_c = 25^\circ C$	40	A
$E_{AS}$	$T_c = 25^\circ C$	1.5	J
$P_D$	$T_c = 25^\circ C$	550	W
$T_J$		-55 ... +175	°C
$T_{JM}$		175	°C
$T_{stg}$		-55 ... +175	°C
$T_L$	1.6mm (0.062 in.) from case for 10s	300	°C
$V_{ISOL}$	$50/60$ Hz, RMS $I_{ISOL} \leq 1mA$	$t = 1min$ $t = 1s$	$2500$ V~ $3000$ V~
$M_d$	Mounting torque Terminal connection torque	1.5/13 1.3/11.5	Nm/lb.in. Nm/lb.in.
<b>Weight</b>		30	g

Symbol	Test Conditions ( $T_J = 25^\circ C$ , unless otherwise specified)	Characteristic Values		
		Min.	Typ.	Max.
$BV_{DSS}$	$V_{GS} = 0V$ , $I_D = 250\mu A$	100		V
$V_{GS(th)}$	$V_{DS} = V_{GS}$ , $I_D = 250\mu A$	2.5	4.5	V
$I_{GSS}$	$V_{GS} = \pm 20V$ , $V_{DS} = 0V$		$\pm 200$	nA
$I_{DSS}$	$V_{DS} = V_{DSS}$ $V_{GS} = 0V$	$T_J = 150^\circ C$	5	$\mu A$
			250	$\mu A$
$R_{DS(on)}$	$V_{GS} = 10V$ , $I_D = 50A$ , Note 1		5.5	$m\Omega$

**Features**

- International standard package
- miniBLOC, with Aluminium nitride isolation
- Avalanche Rated
- Low  $R_{DS(ON)}$  and  $Q_G$
- Low package inductance
- Fast intrinsic Rectifier

**Advantages**

- Low gate charge drive requirement
- High power density

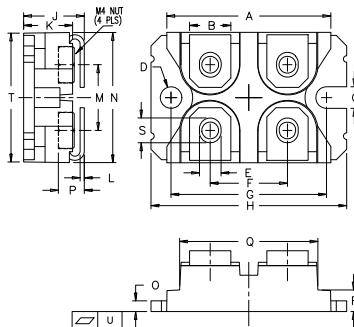
**Applications**

- DC-DC converters
- Battery chargers
- Switched-mode and resonant-mode power supplies
- DC choppers
- AC and DC motor drives
- Uninterrupted power supplies
- High speed power switching applications

Symbol	Test Conditions ( $T_J = 25^\circ\text{C}$ , unless otherwise specified)	Characteristic Values		
		Min.	Typ.	Max.
$g_{fs}$	$V_{DS} = 10\text{V}$ , $I_D = 60\text{A}$ , Note 1	60	96	S
$C_{iss}$ $C_{oss}$ $C_{rss}$	$V_{GS} = 0\text{V}$ , $V_{DS} = 25\text{V}$ , $f = 1\text{MHz}$	9400	pF	
		1087	pF	
		140	pF	
$t_{d(on)}$ $t_r$ $t_{d(off)}$ $t_f$	<b>Resistive Switching Times</b> $V_{GS} = 10\text{V}$ , $V_{DS} = 0.5 \cdot V_{DSS}$ , $I_D = 50\text{A}$ $R_G = 3.3\Omega$ (External)	35	ns	
		31	ns	
		45	ns	
		34	ns	
$Q_{g(on)}$ $Q_{gs}$ $Q_{gd}$	$V_{GS} = 10\text{V}$ , $V_{DS} = 0.5 \cdot V_{DSS}$ , $I_D = 25\text{A}$	152	nC	
		47	nC	
		47	nC	
$R_{thJC}$			0.27	$^\circ\text{C}/\text{W}$
$R_{thCS}$		0.05		$^\circ\text{C}/\text{W}$

**Source-Drain Diode****Characteristic Values** $(T_J = 25^\circ\text{C}$ , unless otherwise specified)

Symbol	Test Conditions	Min.	Typ.	Max.
$I_s$	$V_{GS} = 0\text{V}$		200	A
$I_{SM}$	Repetitive, pulse width limited by $T_{JM}$		500	A
$V_{SD}$	$I_F = 50\text{A}$ , $V_{GS} = 0\text{V}$ , Note 1		1.0	V
$t_{rr}$ $I_{RM}$ $Q_{RM}$	$I_F = 100\text{A}$ , $-di/dt = 100\text{A}/\mu\text{s}$ , $V_R = 50\text{V}$ $V_{GS} = 0\text{V}$	76	ns	
		5.4	A	
		205	nC	

Note 1: Pulse test,  $t \leq 300\mu\text{s}$ ; duty cycle,  $d \leq 2\%$ .**SOT-227B Outline**

SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	1.240	1.255	31.50	31.88
B	.307	.323	7.80	8.20
C	.161	.169	4.09	4.29
D	.161	.169	4.09	4.29
E	.161	.169	4.09	4.29
F	.587	.595	14.91	15.11
G	1.186	1.193	30.12	30.30
H	1.496	1.505	38.00	38.23
J	.460	.481	11.68	12.22
K	.351	.378	8.92	9.60
L	.030	.033	0.76	0.84
M	.496	.506	12.60	12.85
N	.990	1.001	25.15	25.42
O	.078	.084	1.98	2.13
P	.195	.235	4.95	5.97
Q	1.045	1.059	26.54	26.90
R	.155	.174	3.94	4.42
S	.186	.191	4.72	4.85
T	.968	.987	24.59	25.07
U	-.002	.004	-0.05	0.1

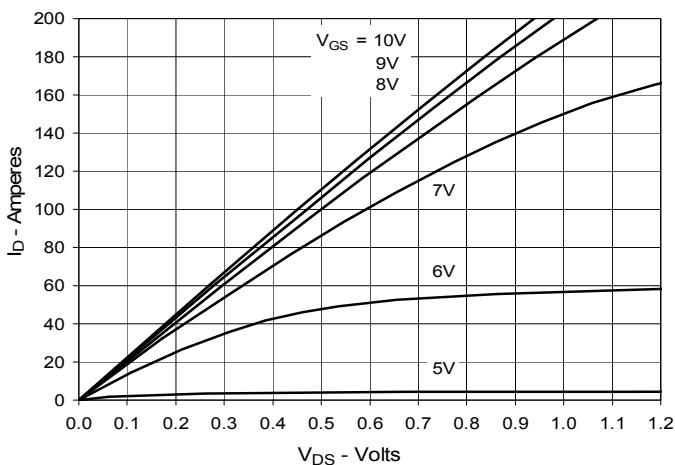
**PRELIMINARY TECHNICAL INFORMATION**

The product presented herein is under development. The Technical Specifications offered are derived from data gathered during objective characterizations of preliminary engineering lots; but also may yet contain some information supplied during a pre-production design evaluation. IXYS reserves the right to change limits, test conditions, and dimensions without notice.

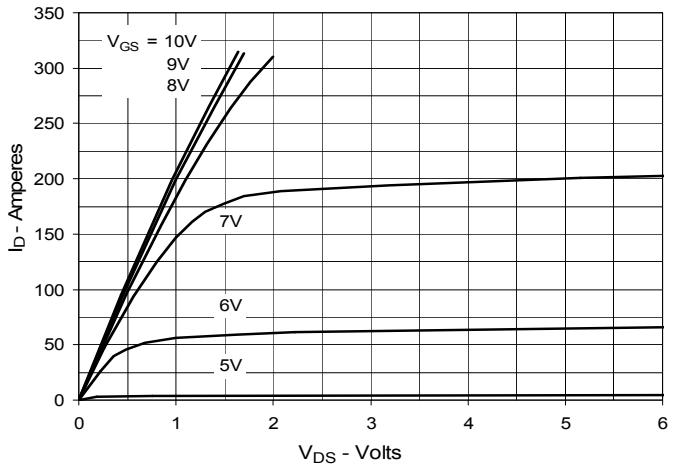
IXYS reserves the right to change limits, test conditions, and dimensions.

IXYS MOSFETs and IGBTs are covered by one or more of the following U.S. patents: 4,835,592 4,931,844 5,049,961 5,237,481 6,162,665 6,404,065 B1 6,683,344 6,727,585 7,005,734 B2 7,157,338B2 5,017,508 5,063,307 5,381,025 6,259,123 B1 6,534,343 6,710,405 B2 6,759,692 7,063,975 B2 4,881,106 5,034,796 5,187,117 5,486,715 6,306,728 B1 6,583,505 6,710,463 6,771,478 B2 7,071,537

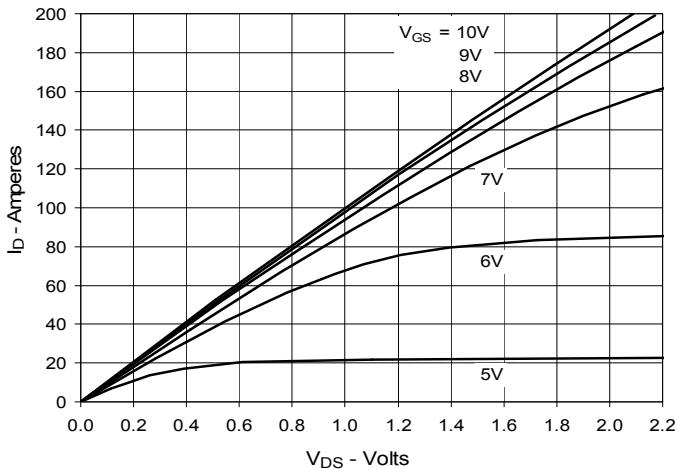
**Fig. 1. Output Characteristics  
@ 25°C**



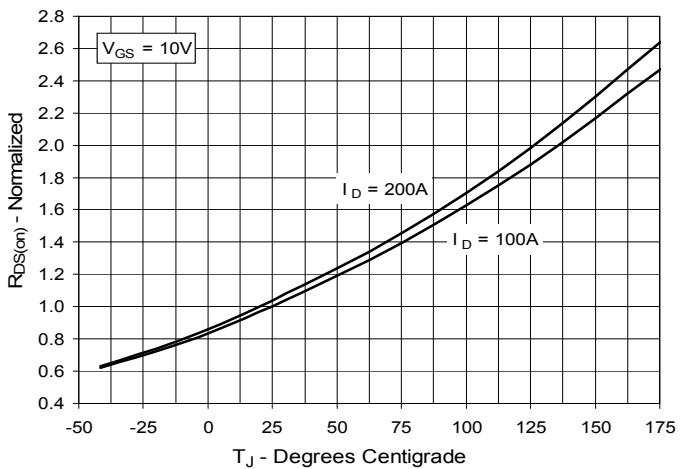
**Fig. 2. Extended Output Characteristics  
@ 25°C**



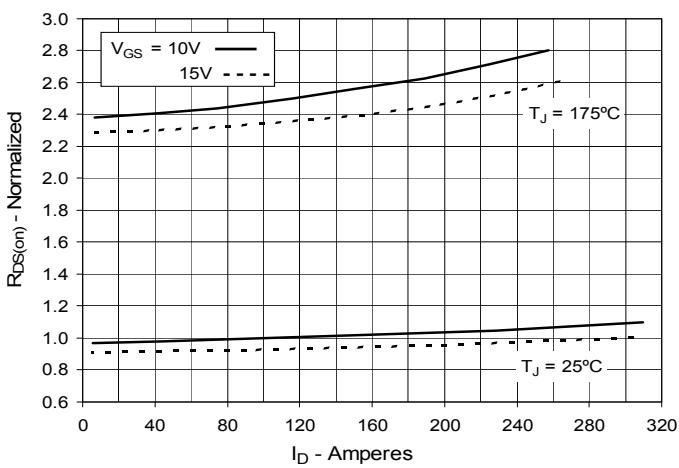
**Fig. 3. Output Characteristics  
@ 150°C**



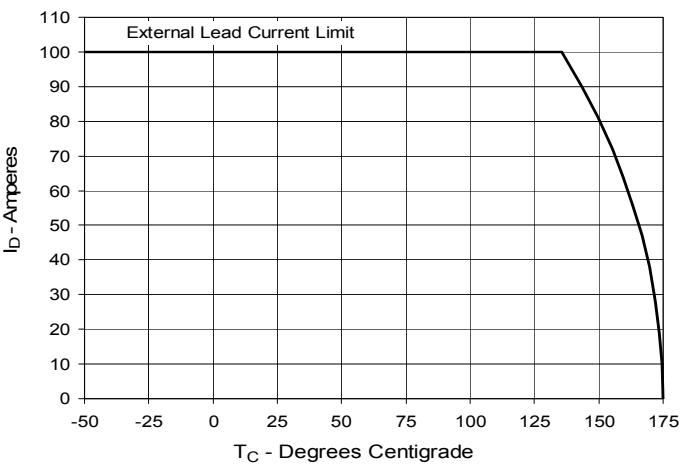
**Fig. 4.  $R_{DS(on)}$  Normalized to  $I_D = 100A$  Value  
vs. Junction Temperature**

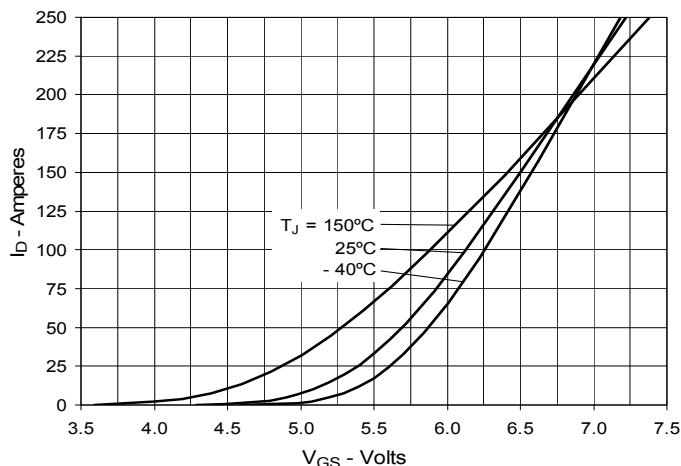
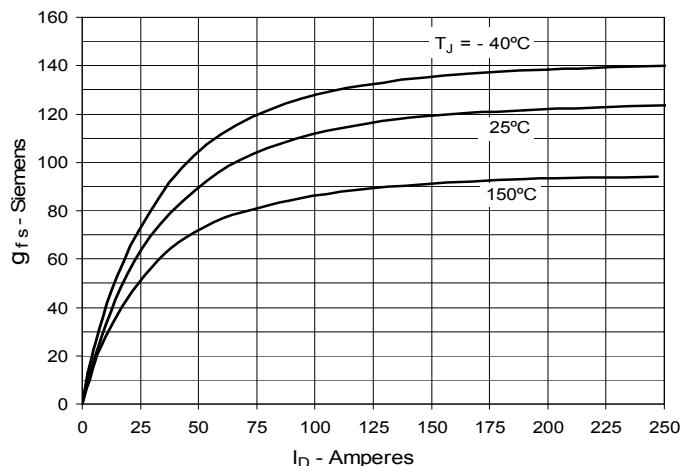
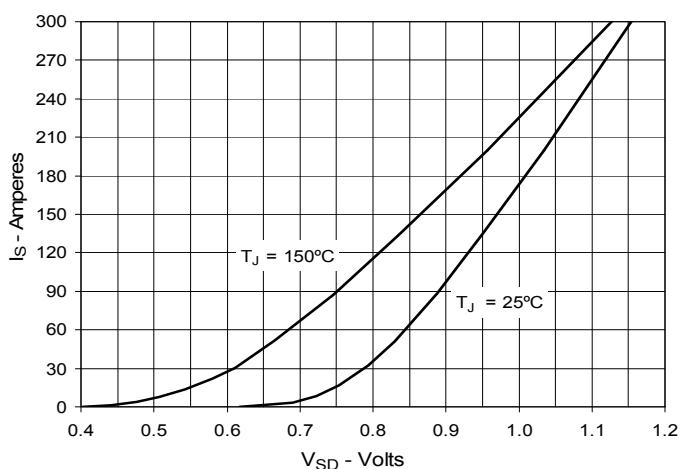
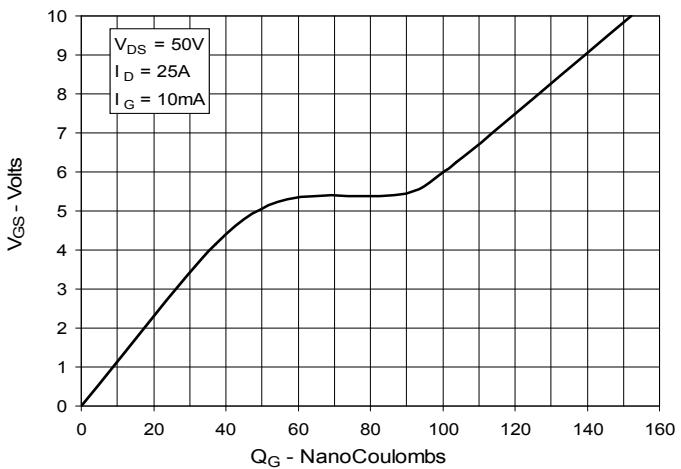
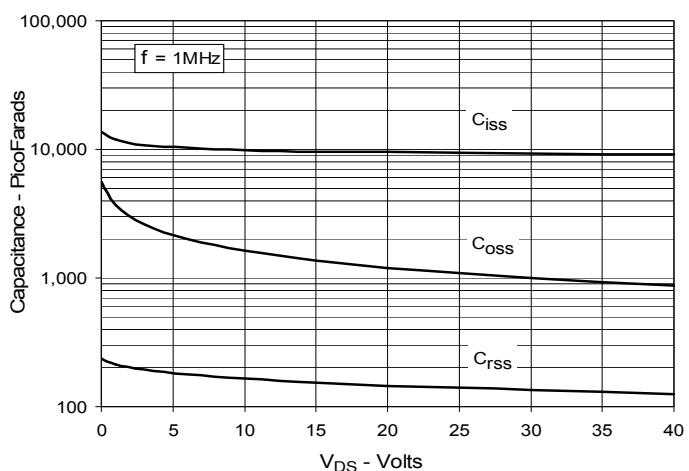
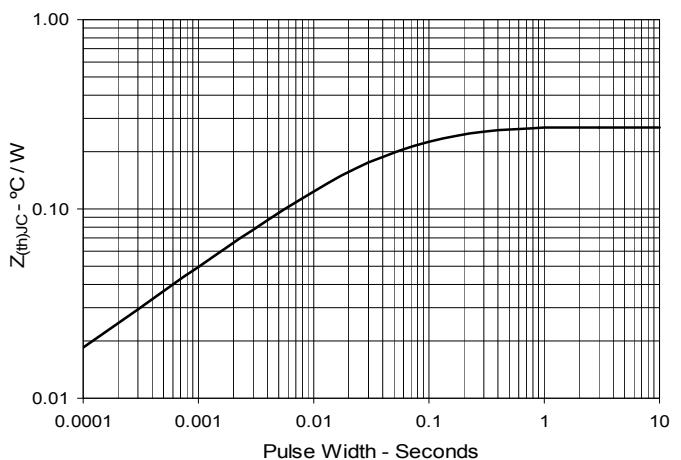


**Fig. 5.  $R_{DS(on)}$  Normalized to  $I_D = 100A$  Value  
vs. Drain Current**

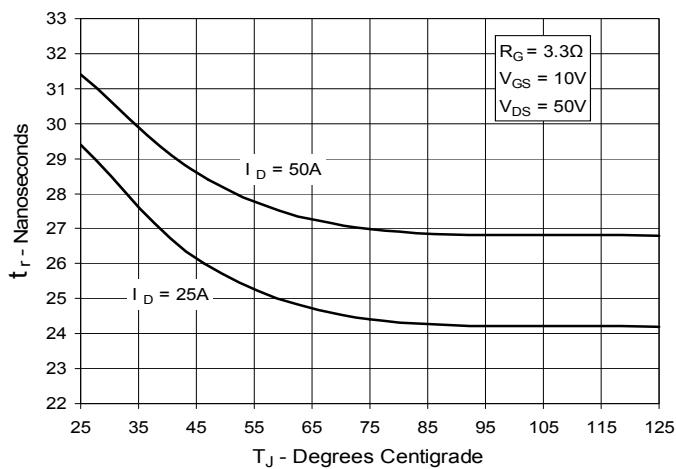


**Fig. 6. Drain Current vs. Case Temperature**

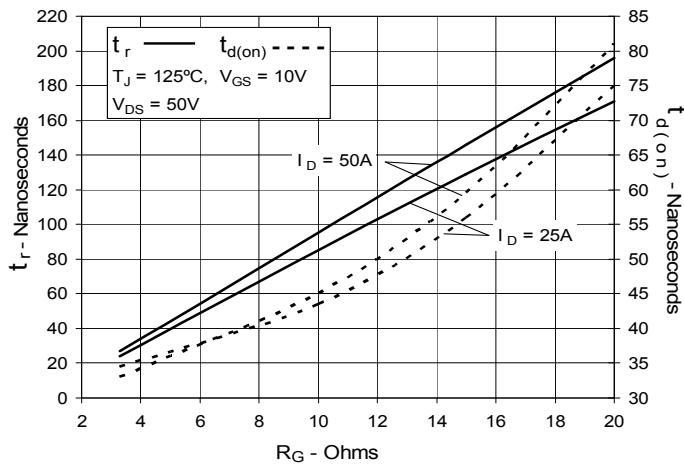


**Fig. 7. Input Admittance****Fig. 8. Transconductance****Fig. 9. Forward Voltage Drop of Intrinsic Diode****Fig. 10. Gate Charge****Fig. 11. Capacitance****Fig. 12. Maximum Transient Thermal Impedance**

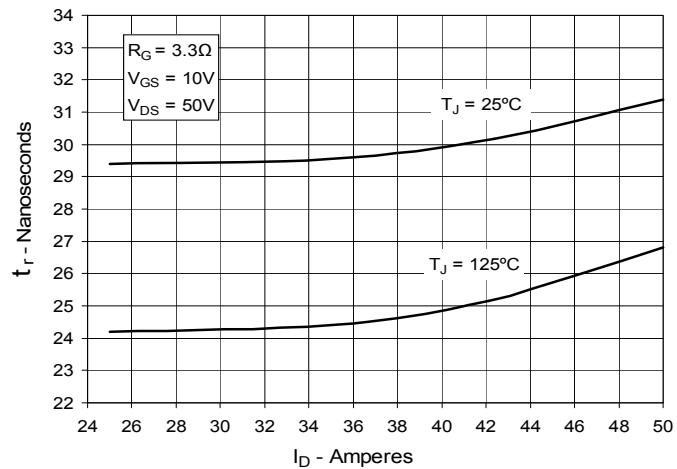
**Fig. 13. Resistive Turn-on  
Rise Time vs. Junction Temperature**



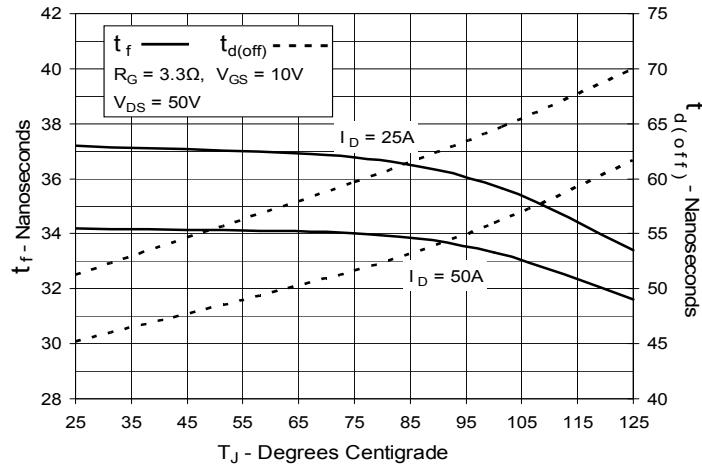
**Fig. 15. Resistive Turn-on  
Switching Times vs. Gate Resistance**



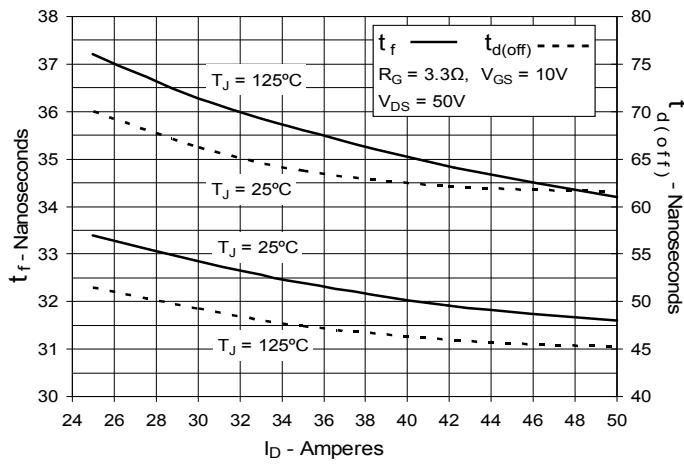
**Fig. 14. Resistive Turn-on  
Rise Time vs. Drain Current**



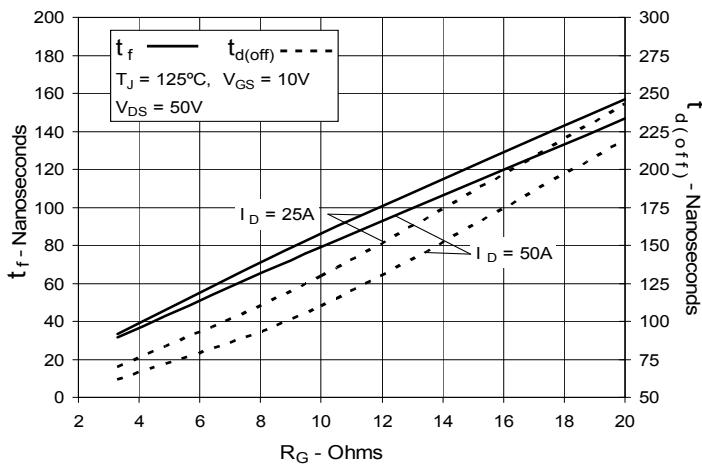
**Fig. 16. Resistive Turn-off  
Switching Times vs. Junction Temperature**



**Fig. 17. Resistive Turn-off  
Switching Times vs. Drain Current**



**Fig. 18. Resistive Turn-off  
Switching Times vs. Gate Resistance**





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